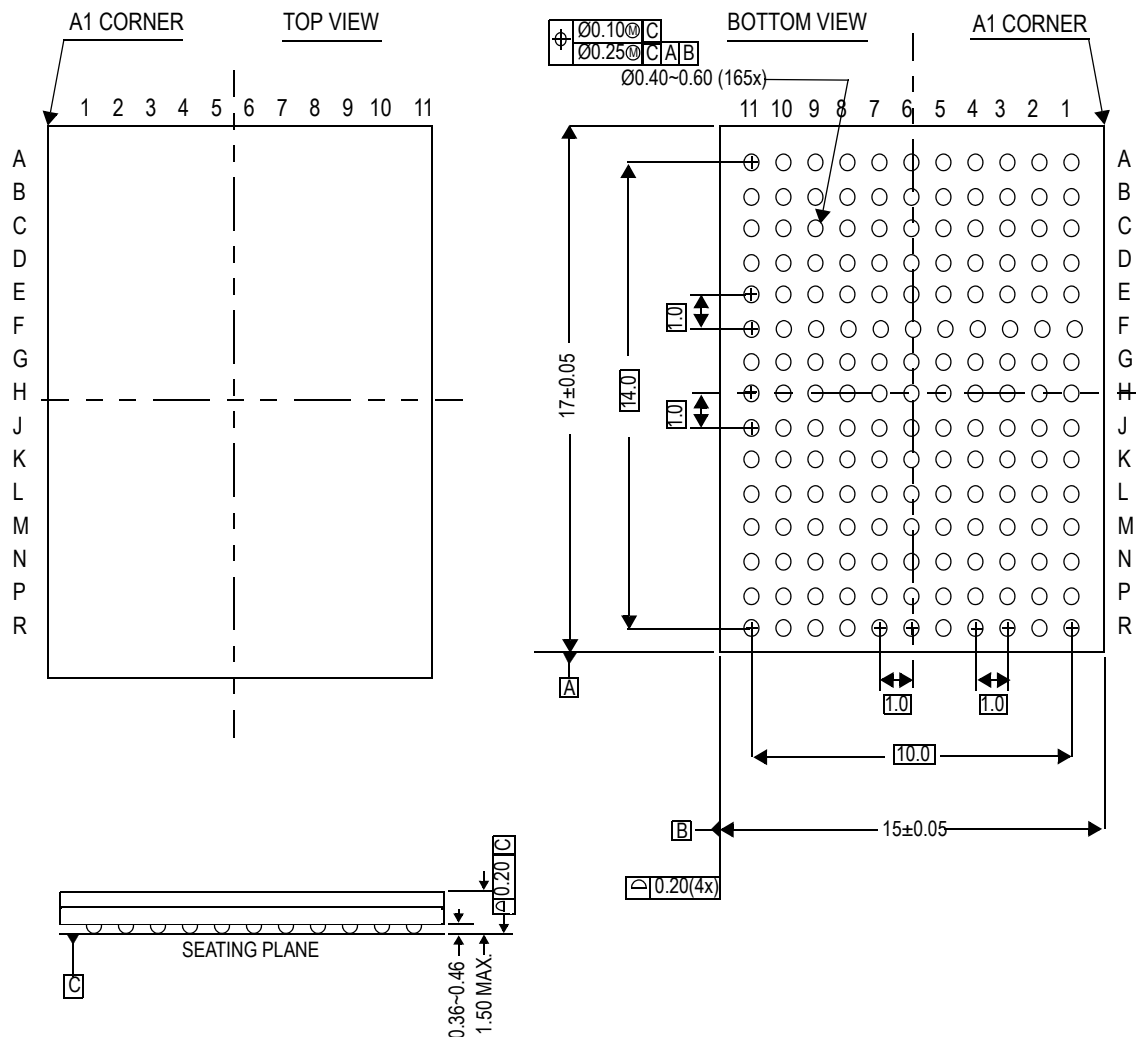


165-Bump BGA (15 mm x 17 mm) DummyDie™ Daisy Chain Package

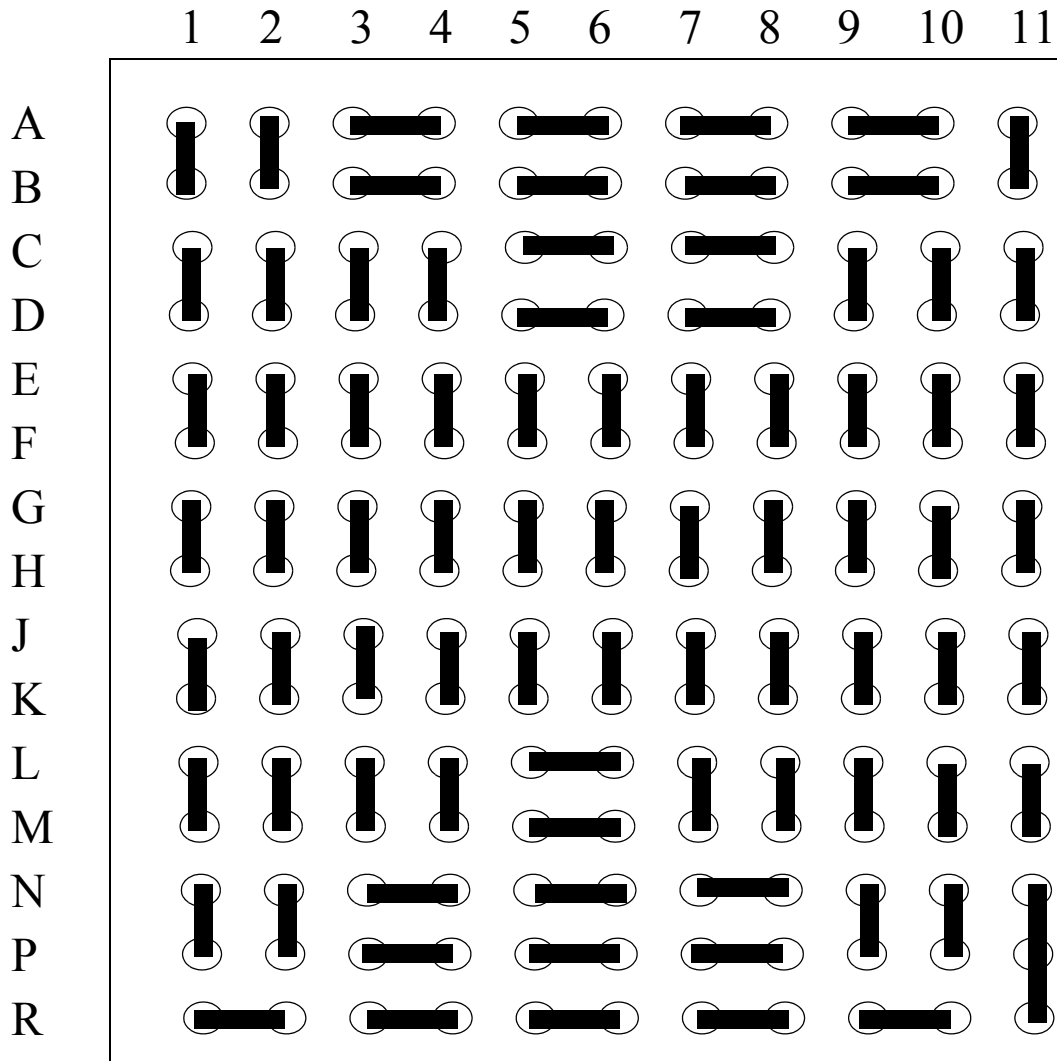
Description

This mechanical daisy chain test vehicle is designed to represent the 165-Bump BGA package. It is used for second level interconnect assembly test and continuity verification. The DummyDie™ incorporates a 10 mm x 15 mm die, which is not electrically connected.

Package Dimensions—165-Bump FPBGA (Package E)



Package Dimensions—165-Bump FPBGA



Ordering Information

165-Bump BGA (15 mm x 17 mm)
Daisy Chain Package

GSDC165ADE



165-Bump BGA (15 mm x 17 mm)
Daisy Chain Package
RoHS-compliant Option

GSDC165ADGE

